

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1935es5#trmpbf

(Engineering Calculation)

TSOT FCOL (FlipChip)

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**TOTAL MASS (g) : 0.01484**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002003	1000000	134974.234375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.005530	975000	372644.875		
		Iron (Fe)	7439-89-6	0.000136	24000	9164.50292969		
		Phosphorus (P)	7723-14-0	0.000002	300	134.772094727		
		Zinc (Zn)	7440-66-6	0.000004	700	269.544189453		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.005672</b>	<b>1000000</b>	<b>382213.65625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000038	1000000	2551.7746582		
		<b>External Plating Total:</b>				<b>0.000038</b>	<b>1000000</b>	<b>2551.7746582</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000000	0	0		
		<b>Internal Plating Total:</b>				<b>0.000000</b>	<b>0</b>	<b>0</b>
Die Attach	75Pb25In	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000875	750000	58962.7929688		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000292	250000	19676.7265625		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000000	0	0		
<b>Die Attach Total:</b>				<b>0.001167</b>	<b>1000000</b>	<b>78639.5234375</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000346	58000	23315.5703125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.005304	890000	357415.59375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000298	50000	20081.0410156		
		Carbon Black (C)	1333-86-4	0.000012	2000	808.632568359		
		<b>Encapsulation Total:</b>				<b>0.005960</b>	<b>1000000</b>	<b>401620.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000000	0	0		
					<b>TOTAL MASS (g) :</b>	<b>0.01484</b>		